IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Composi © Copyright 2005. IPC, international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					Informati	on	
upplier Infor													
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2025-05-14			
Contact Name			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stev	wards	Product I	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
uthorized Repre	sentative*	Title - Re	Title - Representative			Phone - Representative*				Email - Representative*			
Product-Env-Stev	wards	Product I	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Reques	ster Item Number	Mfr Item Number	Mfr Item Name			Effective Date	Version	N	Manufacturing Site		ight*	UOM	Unit Type
		MT9V124EBKSTC	VGA 1/13 SOC			2025-05-14		C	CP2		773	mg	Each
Ianufacturin s	g Proccess Informatio	n											
Termina	al Plating / Grid Array Mater	ial Terminal Ba	Cerminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperature Max Time at Pe		e Max Time at Peak	Temperature	Numb	er of Reflow Cyc	les	
SnAgCu		CU Alloy	CU Alloy 3			260	0 C 30		30	seconds	3		
omments													
TTENTION: MS	SL 3 Rated item requires B	ake and Dry Pack (a	ter electrical test)										
or more informa	tion regarding material con	nposition please refe	to page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this fo											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.69	mg		Misc.	proprietary data		0.0064	mg
			Supplier	Silicon (Si)	7440-21-3		1.6668	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0167	mg
Die Attach	0.16	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.096	mg
			Supplier	Epoxy resins	129915-35-1		0.032	mg
			Supplier	Acrylic resins	Proprietary Data		0.032	mg
Electrode	0.17	mg	Supplier	Titanium (Ti)	7440-32-6		0.0001	mg
			В	Nickel (Ni)	7440-02-0		0.1012	mg
			Supplier	Gold (Au)	7440-57-5		0.0041	mg
			Supplier	Copper (Cu)	7440-50-8		0.0025	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0621	mg
Glass Lid /Cap	7.89	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		1.1204	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.4815	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		0.6312	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.8679	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		0.789	mg
Lid Attach	0.003	mg		Photoinitiator	proprietary data		0.0008	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.0022	mg
Solder Ball	0.14	mg	Supplier	Silver (Ag)	7440-22-4		0.0042	mg
			Supplier	Tin (Sn)	7440-31-5		0.1351	mg
			Supplier	Copper (Cu)	7440-50-8		0.0007	mg
Substrate and Solder Mask	0.72	mg	Supplier	Silica crystalline	14808-60-7, 14464- 46-1		0.072	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		0.342	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		0.306	mg